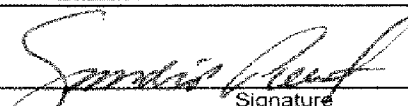


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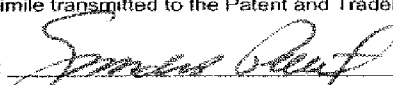
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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

<p>1. Name of conveying party(ies)/Execution Date(s): Cha Deok Dong</p> <p>Execution Date(s): <u>October 29, 2004</u></p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies)</p> <p>Name: <u>HYNIX SEMICONDUCTOR INC.</u></p> <p>Internal Address: _____</p> <p>Street Address: _____</p> <p><u>San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi</u></p> <p>City: <u>Kyungki-Do</u></p> <p>State: _____</p> <p>Country: <u>Republic of Korea</u> Zip: _____</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p>3. Nature of Conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger</p> <p><input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name</p> <p><input type="checkbox"/> Government Interest Assignment</p> <p><input type="checkbox"/> Executive Order 9424, Confirmatory License</p> <p><input type="checkbox"/> Other _____</p>	<p>4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application.</p> <p>A. Patent Application No.(s) <u>11/016,413</u></p> <p>B. Patent No.(s)</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p>5. Name and address to whom correspondence concerning document should be mailed:</p> <p>Name: <u>Sandip H. Patel</u> <u>MARSHALL, GERSTEIN & BORUN LLP</u></p> <p>Internal Address: <u>Atty. Dkt.: 29936/40726</u></p> <p>Street Address: <u>233 S. Wacker Drive, Suite 6300</u> <u>Sears Tower</u></p> <p>City: <u>Chicago</u></p> <p>State: <u>IL</u> Zip: <u>60606-6357</u></p> <p>Phone Number: <u>(312) 474-6300</u></p> <p>Fax Number: <u>(312) 474-0448</u></p> <p>Email Address: _____</p>	<p>6. Total number of applications and patents involved: 1</p> <p>7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>40.00</u></p> <p><input type="checkbox"/> Authorized to be charged by credit card</p> <p><input checked="" type="checkbox"/> Authorized to be charged to deposit account</p> <p><input type="checkbox"/> Enclosed</p> <p><input type="checkbox"/> None required (government interest not affecting title)</p> <p>8. Payment Information</p> <p>a. Credit Card Last 4 Numbers _____ Expiration Date _____</p> <p>b. Deposit Account Number <u>13-2855</u> Authorized User Name <u>Sandip H. Patel</u></p>
<p>9. Signature:</p> <p style="text-align: center;"> Signature</p> <p style="text-align: right;"><u>February 14, 2005</u> Date</p> <p><u>Sandip H. Patel - 43,848</u> Name of Person Signing</p>	<p>Total number of pages including cover sheet, attachments, and documents: 3</p>

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I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office, facsimile no. (703) 306-5995, on the date shown below.

Dated: February 14, 2005 Signature:  (Sandip H. Patel)



ASSIGNMENT

Serial No: 11/016,413

Filed: December 17, 2004

Title: **METHOD OF FORMING POLYSILICON LAYER IN SEMICONDUCTOR DEVICE**

For \$10.00 (Ten Dollars) and other good and sufficient consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to Hynix Semiconductor Inc., of San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, executed by the undersigned on October 29, 2004 and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.



Date: October 29, 2004

Signature: *Chi Deok DONG*
Name: Chi Deok DONG

Date: _____

Signature: _____

Date: _____

Signature: _____

Date: _____

Signature: _____

Date: _____

Signature: _____

Date: _____

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